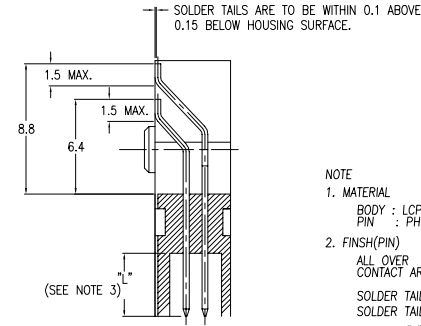
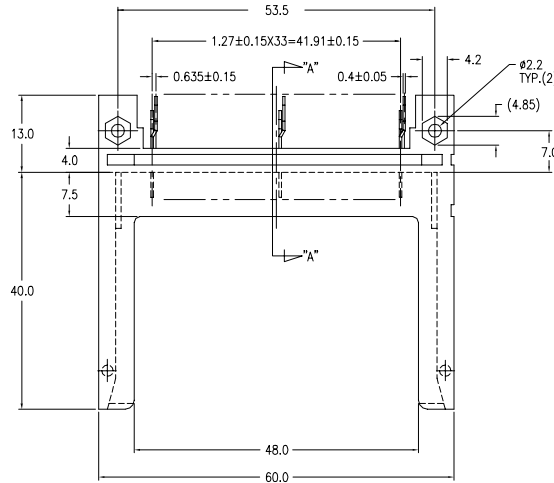
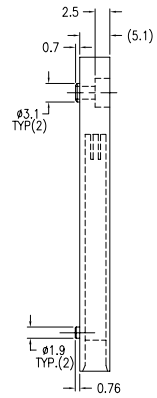


PRODUCT No.
90937-001
90937-001LF

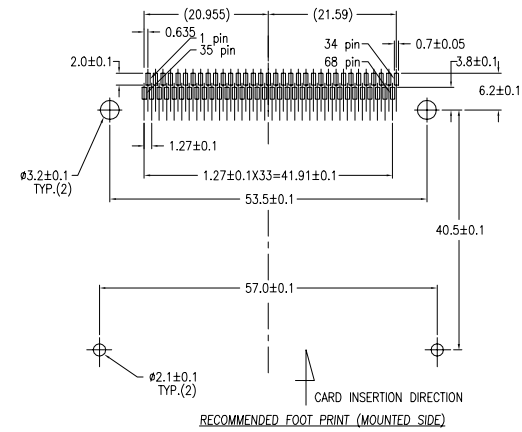
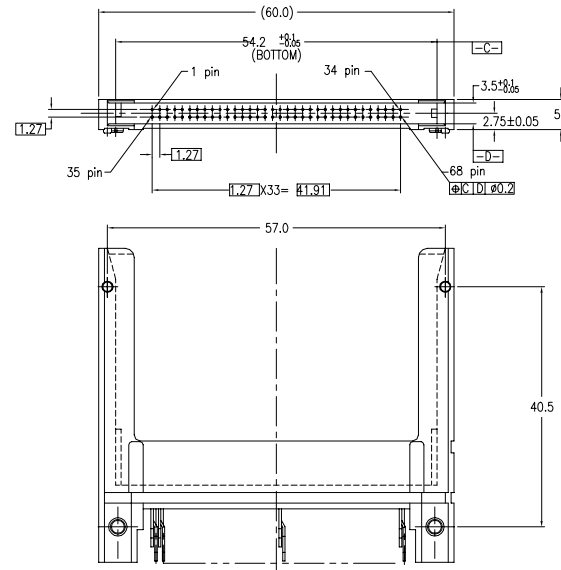


SECTION "A-A" (5/1)

NOTE

- MATERIAL
BODY : LCP UL94V-0 BLACK
PIN : PHOSPHOR BRONZE
- FINSH(PIN)
ALL OVER : Ni UNDER PLATING 0.5um THK MIN.
CONTACT AREA : Au 0.1um THK MIN.
OVER Pd/Ni 0.5um THK MIN.
SOLDER TAIL(Tin Lead option) : Sn/Pd 2.5um THK MIN.
SOLDER TAIL(Lead free option) : Pure Tin 2.5um THK MIN.
- DIMENSION "L"

1,17,34,35,51,68PIN	5.0±0.1
36,67PIN	3.5±0.1
OTHERS	4.25±0.1
- CARD SLOT AND PIN DIMENSIONS PER JEIDA/PCMCIA STANDARDS
- IF LEAD FREE P/N,THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C PEAK TEMPERATURE FOR 10 SECONDS IN A WAVE SOLDER APPLICATION WITH A 1.00MM MINIMUM THICK CIRCUIT BOARD.
- IF LEAD FREE P/N,THE PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DISCRIBLED IN GS-22-008
- LEAD FREE P/N PACKAGING MEETS GS-14-920 SPECIFICATION

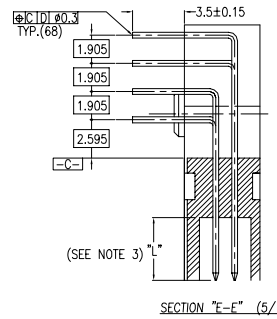
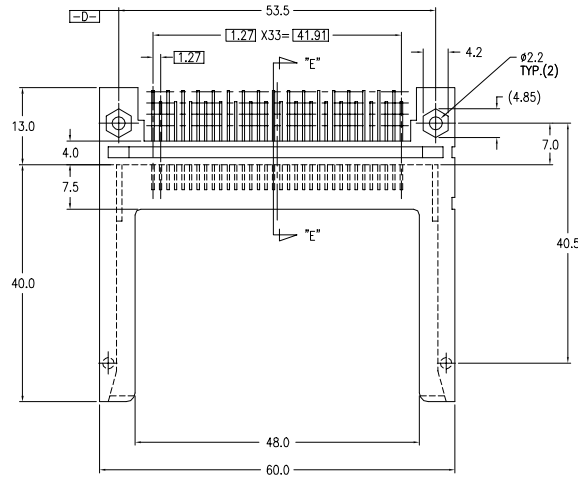
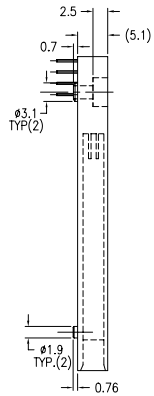


RECOMMENDED FOOT PRINT (MOUNTED SIDE)

mat'l. code	surface	tolerance	projection	product family
	ISO1302	ISO1101 ISO406		MCS
l t r e c n n o d r	date	tolerances unless otherwise specified	MM	title
A J30167 KS 6/1/93	6/1/93	±0.3	scale 2:1	68POS. HEADER ASS'Y
B N06-0031 MZ 03/08/06	03/08/06	0°±2'		JEIDA / PCMCIA TYPE I,II
C ELX-N-011427 ZK 04/23/12	04/23/12			
	dr	S.Ohmori	6/1/93	dwg no
	enr	S.Ohmori	6/1/93	sheet 1 of 4
	chr	S.Ohmori	6/1/93	size
	appd	S.Ohmori	6/1/93	A4
sheet index	revision	c	c	type
	sheet	1	2	Product Customer Drawing

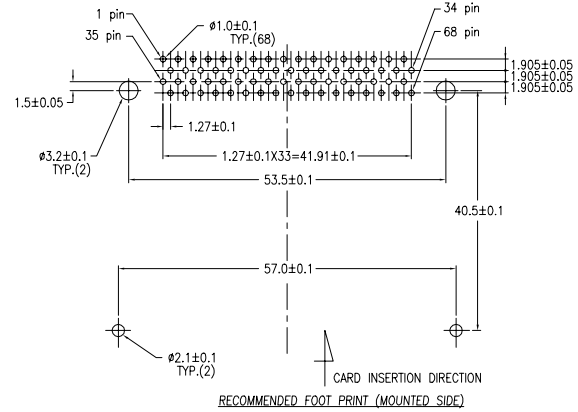
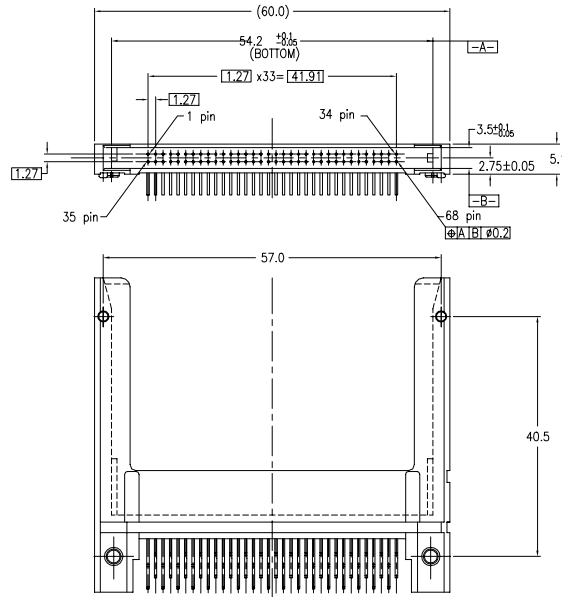


PRODUCT No.
90937-002
90937-002LF



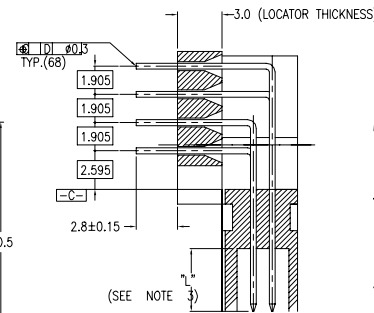
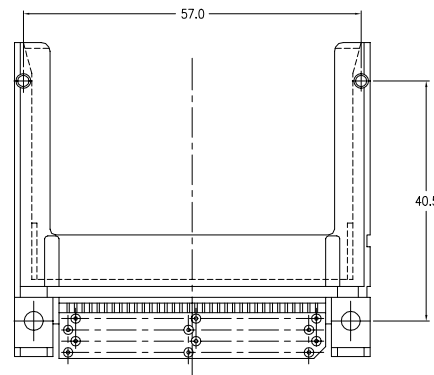
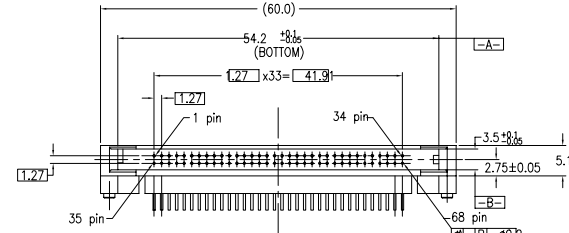
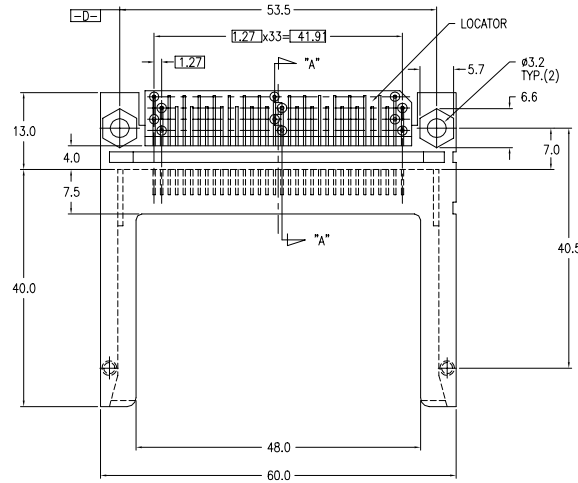
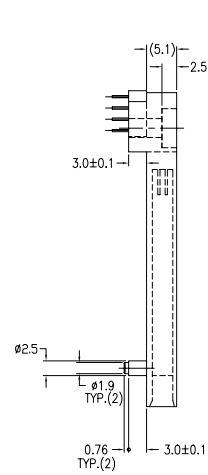
- NOTE
1. MATERIAL
BODY : HIGH TEMPERATURE THERMOPLASTIC UL94V-0 BLACK
PIN : PHOSPHOR BRONZE
 2. FINISH(PIN)
ALL OVER : Ni UNDER PLATING 0.5µm THK MIN.
CONTACT AREA : 0.076 µm MIN. GOLD
SOLDER TAIL(Tin Lead option) : Sn/Pb 2.5µm THK MIN.
SOLDER TAIL(Lead free option) : Pure Tin 2.5µm THK MIN.
 3. DIMENSION "L"

1,17,34,35,51,68PIN	5.0±0.1
36,67PIN	3.5±0.1
OTHERS	4.25±0.1
 4. CARD SLOT AND PIN DIMENSIONS
PER JEIDA/PCMCIA STANDARDS
 5. IF LEAD FREE P/N.THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C PEAK TEMPERATURE FOR 10 SECONDS IN A WAVE SOLDER APPLICATION WITH A 1.00MM MINIMUM THICK CIRCUIT BOARD.
 6. IF LEAD FREE P/N.THE PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DISCRIBLED IN GS-22-008
 7. LEAD FREE P/N PACKAGING MEETS GS-14-920 SPECIFICATION
 8. PRODUCT SPEC:110-263



mat'l. code	surface ISO1302 ✓	tolerance ISO1101 ISO406	projection	product family MCS
l'tecn nodr	tolerances unless otherwise specified		MM	title 68POS. HEADER ASS'Y JEIDA / PCMCIA TYPE I,II
c	angle 0°±2'	±0.3	scale 2:1	sheet 2 of 4 size A4
	dr S.Ohmori	6/1/'93		dwg no 90937
	engr S.Ohmori	6/1/'93		type Product Customer Drawing
	chr S.Ohmori	6/1/'93		
sheet index	revision sheet			

PRODUCT No.
90937-013
90937-013LF

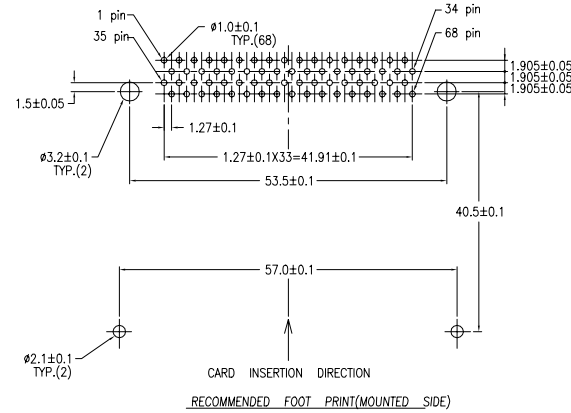


SECTION "A-A" (5/1)

NOTE

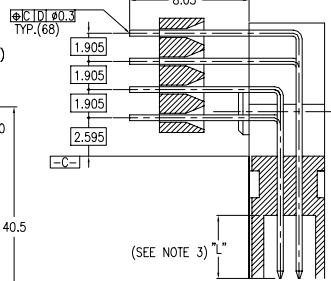
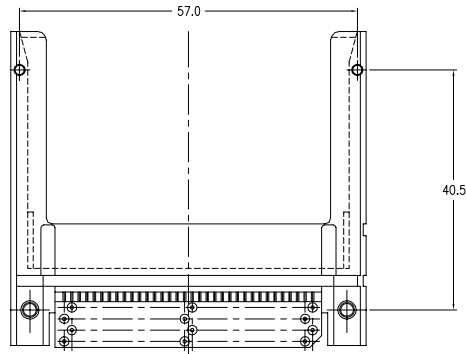
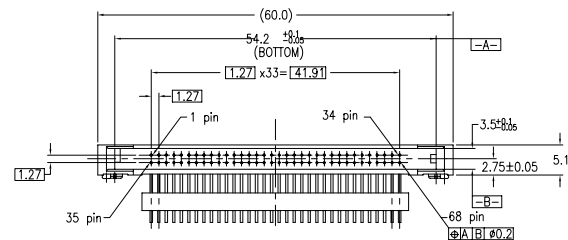
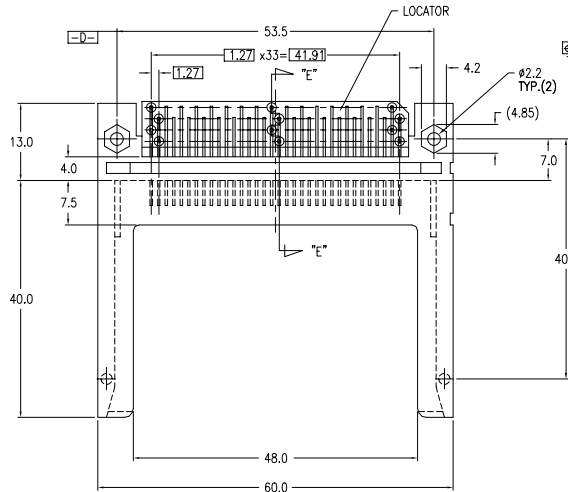
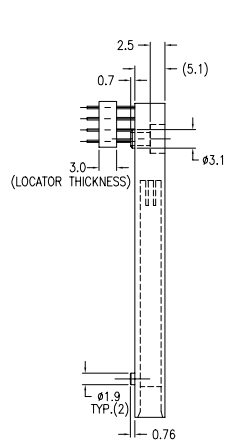
- MATERIAL
BODY : HIGH TEMPERATURE THERMOPLASTIC UL94V-0 BLACK
PIN : PHOSPHOR BRONZE
- FINISH(PIN)
ALL OVER : Ni UNDER PLATING 0.5um THK MIN.
CONTACT AREA : 0.076 µm MIN. GOLD
SOLDER TAIL(Tin Lead option) : Sn/Pb 2.5um THK MIN.
SOLDER TAIL(Lead free option) : Pure Tin 2.5um THK MIN.
- DIMENSION "L"

1,17,34,35,51,68PIN	5.0±0.1
36,67PIN	3.5±0.1
OTHERS	4.25±0.1
- CARD SLOT AND PIN DIMENSIONS PER JEIDA/PCMCIA STANDARDS
- IF LEAD FREE P/N,THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C PEAK TEMPERATURE FOR 10 SECONDS IN A WAVE SOLDER APPLICATION WITH A 1.00MM MINIMUM THICK CIRCUIT BOARD.
- IF LEAD FREE P/N,THE PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DISCRIBED IN GS-22-008
- LEAD FREE P/N PACKAGING MEETS GS-14-920 SPECIFICATION
- PRODUCT SPEC:110-263



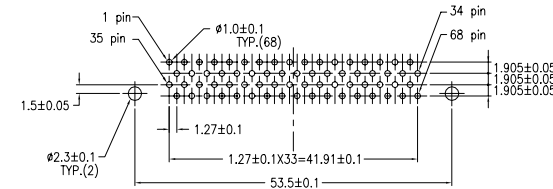
mat'l. code	surface	tolerance	projection	product family
	ISO1302	ISO1101 ISO406		MCS
ltr ecn nodr date	tolerances unless otherwise specified		scale	title
			MM	68POS. HEADER ASS'Y
	angle	±0.3	scale 2:1	JEIDA / PCMCIA TYPE I,II
	0°±2'			
dr	S.Ohmori	6/1/'93		dwg no
engr	S.Ohmori	6/1/'93		sheet 3 of 4
chr	S.Ohmori	6/1/'93		size
appd	S.Ohmori	6/1/'93		A4
sheet index	revision sheet			type Product Customer Drawing

PRODUCT No.
90937-003
90937-003LF



- NOTE
- MATERIAL
BODY : HIGH TEMPERATURE THERMOPLASTIC UL94V-0 BLACK
PIN : PHOSPHOR BRONZE
 - FINISH(PIN)
ALL OVER : Ni UNDER PLATING 0.5um THK MIN.
CONTACT AREA : 0.076 µm MIN. GOLD
SOLDER TAIL(Tin Lead option) : Sn/Pb 2.5um THK MIN.
SOLDER TAIL(Lead free option) : Pure Tin 2.5um THK MIN.
 - DIMENSION "L"

1,17,34,35,51,68PIN	5.0±0.1
36,67PIN	3.5±0.1
OTHERS	4.25±0.1
 - CARD SLOT AND PIN DIMENSIONS PER JEIDA/PCMCIA STANDARDS
 - IF LEAD FREE P/N.THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C PEAK TEMPERATURE FOR 10 SECONDS IN A WAVE SOLDER APPLICATION WITH A 1.00MM MINIMUM THICK CIRCUIT BOARD.
 - IF LEAD FREE P/N.THE PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DISCRIBED IN GS-22-008
 - LEAD FREE P/N PACKAGING MEETS GS-14-920 SPECIFICATION
 - PRODUCT SPEC:110-263



CARD INSERTION DIRECTION
RECOMMENDED FOOT PRINT (MOUNTED SIDE)

mat'l. code	surface ISO1302	tolerance ISO1101 ISO406	projection MM	product family MCS
ltr ecn nodr date	tolerances unless otherwise specified		scale 2:1	title 68POS. HEADER ASS'Y JEIDA / PCMCIA TYPE I,II
c	angle 0°±2'	±0.3	FCI	sheet 4 of 4 size A4
	dr S.Ohmori	6/1/'93		dwg no 90937
	enr S.Ohmori	6/1/'93		type Product Customer Drawing
	chr S.Ohmori	6/1/'93		
	appd S.Ohmori	6/1/'93		
sheet index	revision sheet			